

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	573	438/464.ccls.	US-PGPUB; USPAT	OR	OFF	2006/06/22 07:50
L2	33	((wafer dic\$6 protective) adj tape) same (release adj tape)	US-PGPUB; USPAT	OR	ON	2006/06/22 08:56
L3	3	((wafer dic\$6 protective) adj tape) and (release adj tape)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/22 08:59
L4	75	(438/108.ccls. 438/113.ccls. 438/114.ccls. 438/459.ccls. 438/461.ccls. 438/464.ccls. 438/465.ccls. 438/977.ccls. 29/740.ccls. 29/743.ccls. 156/584. ccls.) and (dbg (dic\$6 near2 grind\$6))	US-PGPUB; USPAT	OR	ON	2006/06/22 09:01
L5	16	"6297131".URPN.	USPAT	OR	OFF	2006/06/22 09:13
L6	46	"5480842".URPN.	USPAT	OR	OFF	2006/06/22 09:14
L7	143	((dbg (dic\$6 near2 grind\$6))) and (semiconductor wafer package chip ic integrated die dice silicon tape)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/22 09:16
L8	221	((438/108.ccls. 438/113.ccls. 438/114.ccls. 438/459.ccls. 438/461.ccls. 438/464.ccls. 438/465.ccls. 438/977.ccls. 29/740.ccls. 29/743.ccls. 156/584. ccls.) and ((wafer dic\$6 protect\$6 releas\$6) adj tape)) and (((die chip) adj pad) leadframe (lead adj frame) ((uv ultraviolet) with adhe\$8))	US-PGPUB; USPAT	OR	ON	2006/06/22 09:48
L9	0	((wafer dic\$6 protect\$6 releas\$6) adj tape) same ((die chip) adj pad) same (leadframe (lead adj frame)) same (((package wiring) adj substrate) carrier module) with (solder adj ball))	US-PGPUB; USPAT	OR	ON	2006/06/22 09:36
L10	10	((wafer dic\$6 protect\$6 releas\$6) adj tape) same (((die chip) adj pad) with (leadframe (lead adj frame) (((package wiring) adj substrate) carrier) with (solder adj ball))))	US-PGPUB; USPAT	OR	ON	2006/06/22 09:36
L11	2	((die chip) adj pad) same (leadframe (lead adj frame)) same ((((package wiring) adj substrate) carrier module) with (solder adj ball))	US-PGPUB; USPAT	OR	ON	2006/06/22 09:38

## EAST Search History

L12	1	((protective adj tape) same (thermal adj degradation))	US-PGPUB; USPAT	OR	ON	2006/06/22 09:41
L13	29	(438/108.ccls. 438/113.ccls. 438/114.ccls. 438/459.ccls. 438/461.ccls. 438/464.ccls. 438/465.ccls. 438/977.ccls. 29/740.ccls. 29/743.ccls. 156/584.ccls.) and ((protect\$6 adj tape) same (adhe\$8 bond\$6) same (heat\$6 thermal\$4 temperature))	US-PGPUB; USPAT	OR	ON	2006/06/22 09:42
L14	29	((((wafer dic\$6 protect\$6 releas\$6) adj tape) and (((die chip) adj pad) leadframe (lead adj frame) ((uv ultraviolet) with adhe\$8))).clm.	US-PGPUB	OR	ON	2006/06/22 09:51